



**MICTOR**

TE Internal #: 2-1658045-2

PCB Mount Header, Vertical, Board-to-Board, 80 Position, .8 mm [.031 in] Centerline, Gold Flash, Surface Mount, Power & Signal, Black

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **80**

Centerline (Pitch): **.8 mm [.031 in]**

**Features**

**Product Type Features**

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

**Configuration Features**

Stackable	No
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	80
Board-to-Board Configuration	Parallel

**Electrical Characteristics**

Dielectric Withstanding Voltage (Max)	675 VAC
Insulation Resistance	2 MΩ
Impedance	100 Ω



Operating Voltage	125 VAC
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### Body Features

Assembly Process Feature Material	Polyimide Film
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Primary Product Color	Black
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### Contact Features

Mating Tab Width	.38 mm[.015 in]
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Mating Tab Thickness	.2 mm[.008 in]
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Contact Shape & Form	Single Beam, Square
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PCB Contact Termination Area Plating Material	Gold
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Contact Base Material	Phosphor Bronze
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Contact Mating Area Plating Material	Gold Flash
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Contact Type	Pin
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Contact Current Rating (Max)	1.25 A, 9.5 A
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### Termination Features

Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
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Rectangular Termination Post & Tail Width	.94 mm[.037 in]
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Termination Method to Printed Circuit Board	Surface Mount
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### Mechanical Attachment

PCB Mount Alignment Type	Locating Posts
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Mating Retention	With
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Mating Alignment	Without
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PCB Mount Retention	With
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PCB Mount Alignment	With
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Connector Mounting Type	Board Mount
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### Housing Features

Centerline (Pitch)	.8 mm[.031 in]
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Housing Material	LCP (Liquid Crystal Polymer)
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### Dimensions

Connector Height	7.06 mm[.278 in]
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	.186 in
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Stack Height	8 mm[.315 in]
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### Usage Conditions

Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
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### Operation/Application

Assembly Process Feature	Pick and Place Cover
Circuit Application	Power & Signal

### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	64
Packaging Type	Box, Tray

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



## Documents

### Product Drawings

[MSB0.80PL8ASY080FL,-,F,-TY](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2-1658045-2\\_H.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2-1658045-2\\_H.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2-1658045-2\\_H.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Datasheets & Catalog Pages



## MICTOR SB Interconnection System

English

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### Product Specifications

#### Application Specification

English

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### Agency Approvals

#### UL Report

English